

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6437535

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	MONOLITHIC 3D INC.	11/17/2020
RECEIVING PARTY DATA		
Name:	SAMSUNG ELECTRONICS CO., LTD.	
Street Address:	129 SAMSUNG-RO, YEONGTONG-GU	
City:	SUWON-SI, GYEONGGI-DO	
State/Country:	KOREA, REPUBLIC OF	
Postal Code:	16677	
PROPERTY NUMBERS Total: 21		
Property Type	Number	
Patent Number:	8405420	
Patent Number:	8237228	
Patent Number:	8058137	
Patent Number:	8153499	
Patent Number:	7960242	
Patent Number:	8541819	
Patent Number:	8362482	
Patent Number:	8258810	
Patent Number:	8912052	
Patent Number:	8754533	
Patent Number:	8836073	
Patent Number:	8362800	
Patent Number:	8994404	
Patent Number:	9142553	
Patent Number:	8026521	
Patent Number:	8203148	
Patent Number:	8956959	
Patent Number:	9818800	
Patent Number:	9953994	
Patent Number:	10297599	

PATENT

Property Type	Number
Patent Number:	10622365
CORRESPONDENCE DATA	
Fax Number:	(703)668-8200
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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ATTORNEY DOCKET NUMBER:	2557-503306
NAME OF SUBMITTER:	JOHN A. CASTELLANO
SIGNATURE:	/John A. Castellano/
DATE SIGNED:	12/08/2020
Total Attachments: 4 source=Assignment#page1.tif source=Assignment#page2.tif source=Assignment#page3.tif source=Assignment#page4.tif	

ASSIGNMENT

Monolithic 3D™ Inc., a State of Texas corporation (EIN# 26-4825477) ("Assignor") declares that it is the sole owner of the patents and patent applications set forth on Attachment 1 hereto.

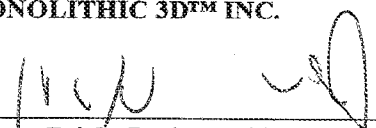
For valuable consideration, the receipt and adequacy of which is hereby acknowledged, Assignor hereby sells, assigns, and transfers unto Samsung Electronics Co., Ltd., a Korean corporation with its principal place of business at 129 Samsung-Ro, Yeongtong-Gu, Suwon City, Gyeonggi-D, 16677 Korea (the "Assignee"), the sole and entire right, title, and interest that exist today and may exist in the future in and to the patents and patent applications set forth on Attachment 1 hereto, including all rights pursuant to 35 U.S.C. § 154 and any and all Letters Patent issuing therefrom, and any and all reissues, reexaminations, extensions, continuations, continuations-in-part, divisionals, provisionals, substitutions, renewals, and registrations of any item in the foregoing; all inventions described in any of the foregoing; and any and all patents, patent applications and counterparts arising from any item in the foregoing (the "Assigned Patents"); and all past, present, and future causes of action and claims for damages derived by reason of patent infringement thereof, for said Assignee's own use and for the use of its assigns, successors, and legal representatives to the full end of the term of each of the Assigned Patents.

Assignor, for itself, and its heirs, assigns, and legal representatives hereby further covenants to and with Assignee, its assigns, successors, and legal representatives to fully cooperate therewith in perfecting this assignment in the United States and in any and all foreign jurisdictions, said cooperation extending to the Assigned Patents, and including the execution of additional assignments or other formal documents as may be required in connection therewith.

Assignor hereby authorizes the respective patent office or governmental agency in each jurisdiction to issue any and all patents, certificates of invention, utility models or other governmental grants or issuances that may be granted upon any of the Assigned Patents in the name of Assignee, as the assignee to the entire interest therein.

IN WITNESS WHEREOF this Assignment is executed on November 17, 2020.

MONOLITHIC 3D™ INC.


Name: Zvi Or-Bach, President and CEO

Date: November 17, 2020

Attachment 1

Patents

Family	Patent No. / Publication No.	Title of Invention	Field of Technology
1	US8,405,420	System comprising a semiconductor device and structure	Logic
	US8,237,228	System comprising a semiconductor device and structure	
	US8,058,137	Method for fabrication of a semiconductor device and structure	
	US8,153,499	Method for fabrication of a semiconductor device and structure	
	US7,960,242	Method for fabrication of a semiconductor device and structure	
	US8,541,819	Semiconductor device and structure	
	US8,362,482	Semiconductor device and structure	
	US8,258,810	3D semiconductor device	
	US8,912,052	Semiconductor device and structure	
	US8,754,533	Monolithic three-dimensional semiconductor device and structure	
	US8,836,073	Semiconductor device and structure	
2	US8,362,800	3D semiconductor device including field repairable logics	
3	US8,994,404	Semiconductor device and structure	
	US9,142,553	Semiconductor device and structure	
4	US8,026,521	Semiconductor device and structure	Memory
	US8,203,148	Semiconductor device and structure	
	US8,956,959	Method of manufacturing a semiconductor device with two monocrystalline layers	
	US9,818,800	Self aligned semiconductor device and	

		structure	
5	US9,953,994	Semiconductor memory device and structure	
6	US10,297,599	Semiconductor memory device and structure	
7	US10,622,365	Semiconductor memory device and structure	

ATTESTATION OF SIGNATURE

The undersigned, Liran Mergui, witnessed the signature of Zvi Or-Bach to the above Assignment on behalf of Monolithic 3D™ Inc. and makes the following statements:

1. I am over the age of 18 and competent to testify as to the facts in this Attestation block if called upon to do so.
2. Zvi-Or Bach is personally known to me (or proved to me on the basis of US passport number 566475007) and appeared before me on November 17, 2020 to execute the above Assignment on behalf of Monolithic 3D™ Inc.
3. Zvi-Or Bach signed the above Assignment on behalf of Monolithic 3D™ Inc.

EXECUTED on November 17, 2020



Print Name: Liran Mergui

PATENT

RECORDED: 12/08/2020

REEL: 054576 FRAME: 0691